

Commission Delegated Directive (EU) 2019/172 of 16 November 2018 amending, for the purposes of adapting to scientific and technical progress, Annex III to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages (Text with EEA relevance)

- Article 1 Annex III to Directive 2011/65/EU is amended as set out...
- Article 2 (1) Member States shall adopt and publish, by 29 February 2020...
- Article 3 This Directive shall enter into force on the twentieth day...
- Article 4 This Directive is addressed to the Member States.
- Signature

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#### ANNEX

In Annex III, entry 15 is replaced by the following:...

15 Lead in solders to complete a viable electrical connection...

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**Status:** EU Directives are being published on this site to aid cross referencing from UK legislation. After  
IP completion day (31 December 2020 11pm) no further amendments will be applied to this version.

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- (1) [OJ L 174, 1.7.2011, p. 88.](#)
- (2) Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006 concerning the Registration, Evaluation, Authorisation and Restriction of Chemicals (REACH) and establishing a European Chemicals Agency ([OJ L 396, 30.12.2006, p. 1](#)).